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Enclosure to letter dated 05 August 2004 concerning European Patent Appln. No. PCT/NL03/00874; -DSM IP Assets B.V.-; ref. 21433WO.

AMENDED CLAIMS

1. Flame retardant polyamide compound comprising a polyamide polymer having a weight-average molecular weight of at least 10.000 g/mol, a halogen-free flame retardant and a polyamide oligomer having a weight-average molecular weight of at most 7500, and wherein the polyamide oligomer is a melt-processable semi-crystalline or amorphous polyamide, characterized in that the halogen-free flame retardant is a halogen-free phosphorous containing flame retardant.
2. Compound according to claim 1, wherein the polyamide oligomer is a polyamide with a melting temperature of at least 260°C.
3. Compound according to claim 1 or 2, wherein the polyamide oligomer is present in an amount of 0.1-30 weight %, relative to the total weight of polyamide.
4. Compound according to any of claims 1-3, wherein the halogen-free phosphorous containing flame retardant is a melamine based phosphorous compound.
5. Compound according to any of claims 1-4, wherein phosphorous containing flame retardant is present in an amount between 1 and 100 parts by weight, relative to a total amount of polyamide of 100 parts by weight.
6. Process for preparing a compound according to any of claims 1-5 comprising melt-mixing of a polyamide composition comprising a polyamide polymer having a weight-average molecular weight of at least 10.000 g/mol, a polyamide oligomer having a weight-average molecular weight of at most 7500, and a halogen-free phosphorous containing flame retardant.
7. Process according to claim 6, wherein the polyamide polymer is a polyamide with a melting temperature of at least 260°C.
8. Process according to any of claims 6-7, wherein the polyamide oligomer has a melting temperature of at most 20°C above the melting temperature of the polyamide polymer.
9. Process according to any of claims 1-5, wherein the polyamide compound comprises a reinforcing component.
10. Use of a polyamide compound according to any of claims 1-6 for the preparation of a molded part.
11. Molded part obtainable by melt-processing of a polyamide compound according to any of claims 1-6.